



#19/1  
10/16/02  
Sullivan

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Tabrizi, B.

Atty. Dkt. 1920/107

Serial No.: 09/677,291

Art Unit: 2815

Date Filed: October 2, 2000

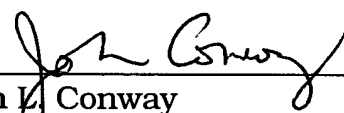
Examiner: C. Chu

Invention: SEMICONDUCTOR PACKAGING

\*\*\*\*\*

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to Box RCE, Commissioner for Patents, Washington, D.C. 20231 on October 3, 2002.

  
\_\_\_\_\_  
John L. Conway

Box RCE  
Commissioner for Patents  
Washington, DC 20231

\*\*\*\*\*

RECEIVED  
OCT 10 2002  
TECHNOLOGY CENTER 2800

**RESPONSE D**

Dear Sir:

In response to the Office Action mailed on June 4, 2002 and made final, entry of the following amendments is requested.

**In the Claims:**

Please cancel claims 3 and 33.

Please amend claims 1, 9, 14, 16, 21, 22, and 32 as follows:

1. (amended) An electronic component comprising:

DI an electronic device package including a silicon wafer having a recess,  
the recess including a conductive region; and